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MATSUTOMI et al.(10) **Pub. No.: US 2022/0386453 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **WIRING CIRCUIT BOARD AND METHOD
OF PRODUCING THE SAME****Publication Classification**(71) Applicant: **NITTO DENKO CORPORATION,**
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ABSTRACT

A wiring circuit board includes a porous insulating layer, and a first conductive layer sequentially toward one side in the thickness direction. The first conductive layer includes a first signal wire and first ground wires. Each of the first ground wires is thicker than the first signal wire.

